

Silicon Carbide Power MOSFET

C3M™ MOSFET Technology

N-Channel Enhancement Mode

Features

- · 3rd generation SiC MOSFET technology
- · Optimized package with separate driver source pin
- High blocking voltage with low on-resistance
- · High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery (Q_{rr})
- · Halogen free, RoHS compliant

Benefits

- · Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- · Increase system switching frequency

Typical Applications

- Datacenter Power Supplies
- Telecom Power Supplies
- Energy Storage Systems
- Solar (PV) inverters
- High Voltage DC/DC converters

Package

Drain Tab









Orderable Part Number	Package	Marking
C3M0120065L-TR	TOLL	C3M0120065L

Key Parameters

Parameter	Symbol	Min.	Тур.	Max	Unit	Conditions	Note
Drain - Source Voltage	V _{DS}			650		T _c = 25°C	
Maximum Gate - Source Voltage	V _{GS(max)}	-8		+19	v	Transient	
Operational Gate-Source Voltage	V _{GS op}		-4/15			Static	Note 1
				21		$V_{GS} = 15 \text{ V}, T_{C} = 25 \text{ °C}, T_{J} \le 175 \text{ °C}$	Fig. 19
DC Continuous Drain Current	I _D			14	A	$V_{GS} = 15 \text{ V}, T_{C} = 100 \text{ °C}, T_{J} \le 175 \text{ °C}$	Note 2
Pulsed Drain Current	I _{DM}			51		t_{pmax} limited by T_{jmax} $V_{GS} = 15V, T_{C} = 25 °C$	Fig. 22
Power Dissipation	P _D			86	W	$T_{c} = 25 ^{\circ} \text{C}, T_{J} = 175 ^{\circ} \text{C}$	Fig. 20
Junction Temperature	T _J			-40 to +175			
Case and Storage Temperature	T_{C},T_{stg}			-40 to +150	°C		
Solder Temperature	T _L			260		According to JEDEC J-STD-020	

 $Note~(1): Recommended~turn-on~gate~voltage~is~15V~with~\pm 5\%~regulation~tolerance, see~Application~Note~PRD-04814~for~additional~details~tolerance, see~Application~details~tolerance, see~Applicat$

Note (2): Verified by design

Electrical Characteristics ($T_c = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	650			٧	V _{GS} = 0 V, I _D = 100 μA	
V	Gate Threshold Voltage	1.8	2.3	3.6	V	V _{DS} = V _{GS} , I _D = 1.86 mA	Fig. 11
$V_{GS(th)}$			1.9		V	V _{DS} = V _{GS} , I _D = 1.86 mA, T _J = 175°C	
I _{DSS}	Zero Gate Voltage Drain Current		1	50	μΑ	$V_{DS} = 650 \text{ V, } V_{GS} = 0 \text{ V}$	
I _{GSS}	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 15 \text{ V}, V_{DS} = 0 \text{ V}$	
D	Drain-Source On-State Resistance		120	157	mΩ	V _{GS} = 15 V, I _D = 6.76 A	Fig. 4,
$R_{DS(on)}$	Dialif-Source Off-State Resistance		168		11112	V _{GS} = 15 V, I _D = 6.76 A, T _J = 175°C	5, 6
a	Transconductance		5		s	V _{DS} = 20 V, I _{DS} = 6.76 A	Fi 7
G fs	Transconductance		5			V _{DS} = 20 V, I _{DS} = 6.76 A, T _J = 175°C	Fig. 7
C _{iss}	Input Capacitance		640			V _{GS} = 0 V, V _{DS} = 400 V	Fig. 17, 18
Coss	Output Capacitance		45		pF	F = 1 Mhz	
C _{rss}	Reverse Transfer Capacitance		2.3			Vac = 25 mV	
E _{oss}	C _{oss} Stored Energy		9		μJ	V _{DS} = 600 V, F = 1 Mhz	Fig. 16
$C_{\text{o(er)}}$	Effective Output Capacitance (Energy Related)		57		pF	V _{GS} = 0 V, V _{DS} = 0 400V	Note: 3
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		79		pF		
Eon	Turn-On Switching Energy (Body Diode FWD)		27			$V_{DS} = 400 \text{ V}, V_{GS} = -4 \text{ V}/15 \text{ V}, I_{D} = 6.76 \text{A},$	Fig. 23
E _{OFF}	Turn-Off Switching Energy (Body Diode FWD)		7		μJ	$R_{G(ext)}$ = 10 Ω, L= 237 μH, T_J = 25°C FWD = Internal Body Diode	
$t_{\text{d(on)}}$	Turn-On Delay Time		5				
t _r	Rise Time		10		V_{DD} = 400 V, V_{GS} = -4 V/15 V I_{D} = 6.76 A, $R_{G(ext)}$ = 10 Ω ,	Fin 06	
t _{d(off)}	Turn-Off Delay Time		18		ns	Timing relative to V _{DS}	Fig. 26
t _f	Fall Time		9			inductive road	
R _{G(int)}	Internal Gate Resistance		6		Ω	f = 1 MHz, V _{AC} = 25 mV	
Q_{gs}	Gate to Source Charge		8			V _{DS} = 400 V, V _{GS} = -4 V/15 V	Fig. 12
Q_{gd}	Gate to Drain Charge		7		nC	I _D = 6.76 A	
Q_g	Total Gate Charge		26			Per IEC60747-8-4 pg 21	

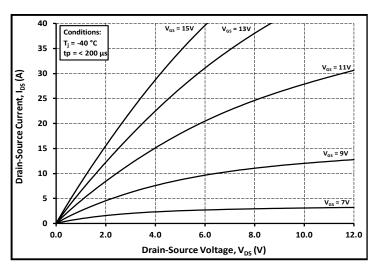
Note (3): $C_{O(er)}$, a lumped capacitance that gives same stored energy as Coss while Vds is rising from 0 to 400V $C_{O(tr)}$, a lumped capacitance that gives same charging time as Coss while Vds is rising from 0 to 400V

Reverse Diode Characteristics ($T_c = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V	Die de Ferrand Velteren	4.5		٧	$V_{GS} = -4 \text{ V, I}_{SD} = 3.4 \text{ A, T}_{J} = 25 \text{ °C}$	Fig. 8,
V _{SD}	Diode Forward Voltage	4.0		٧	V _{GS} = -4 V, I _{SD} = 3.4 A, T _J = 175 °C	9, 10
Is	Continuous Diode Forward Current		14	Α	V _{GS} = -4 V, T _C = 25°C	
I _{S, pulse}	Diode pulse Current		51	Α	V_{GS} = -4 V, pulse width t_P limited by T_{jmax}	
t _{rr}	Reverse Recover time	7		ns	V _{GS} = -4 V, I _{SD} = 6.76 A, V _R = 400 V dif/dt = 7880 A/μs, T _J = 25 °C	
Q _{rr}	Reverse Recovery Charge	93		nC		
I _{rrm}	Peak Reverse Recovery Current	23		Α		
t _{rr}	Reverse Recover time	8		ns	V _{GS} = -4 V, I _{SD} = 6.76 A, V _R = 400 V dif/dt = 2320 A/μs, T ₁ = 25 °C	
Q _{rr}	Reverse Recovery Charge	45		nC		
I _{rrm}	Peak Reverse Recovery Current	9		Α	3, at 2020 / 4, po, 1, 20 0	

Thermal Characteristics

Symbol	Parameter	Тур.	Unit	Test Conditions	Note
$R_{ heta JC}$	Thermal Resistance from Junction to Case	1.38	°C/W		Fig. 21



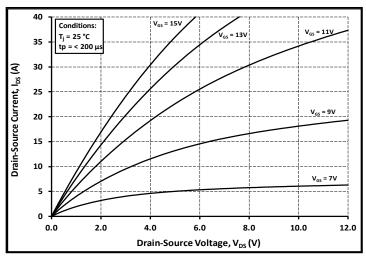
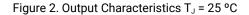
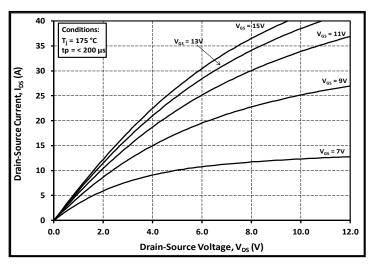


Figure 1. Output Characteristics T_J = -40 °C





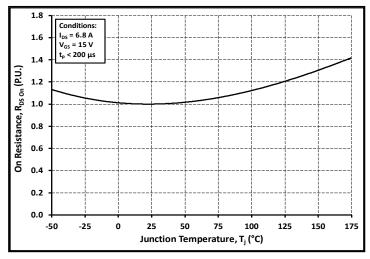
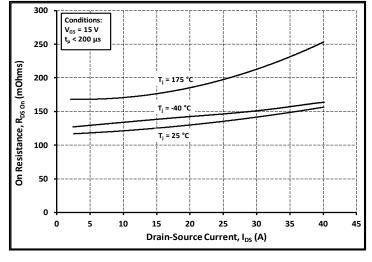


Figure 3. Output Characteristics T_J = 175 °C

Figure 4. Normalized On-Resistance vs. Temperature



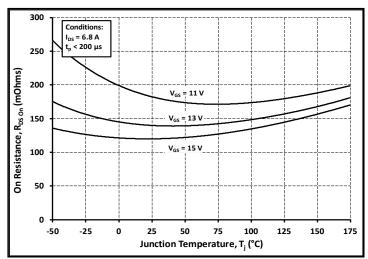


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

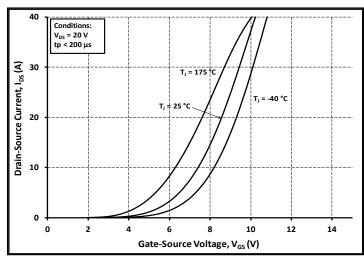


Figure 7. Transfer Characteristic for Various Junction Temperatures

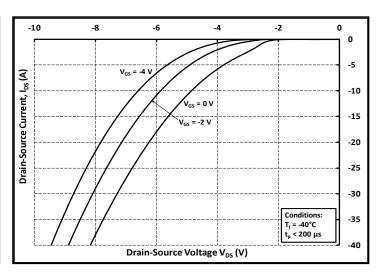


Figure 8. Body Diode Characteristic at -40 °C

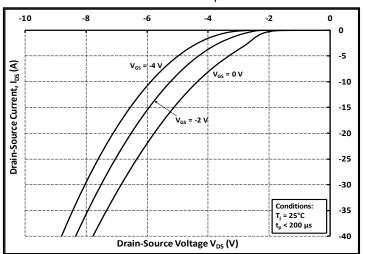


Figure 9. Body Diode Characteristic at 25 °C

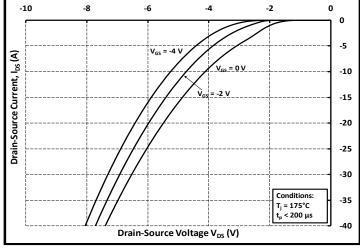


Figure 10. Body Diode Characteristic at 175 °C

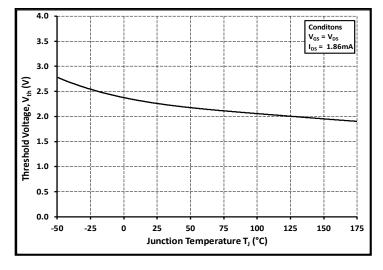


Figure 11. Threshold Voltage vs. Temperature

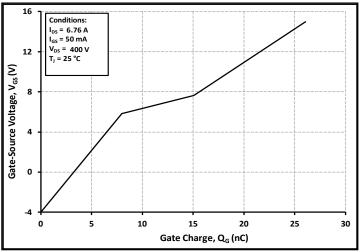
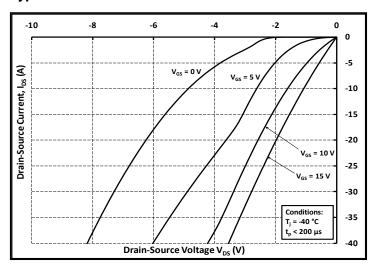


Figure 12. Gate Charge Characteristics



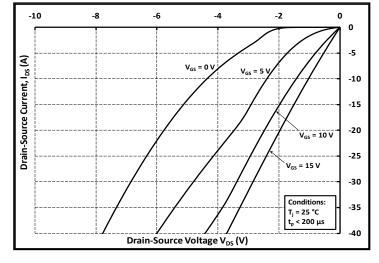
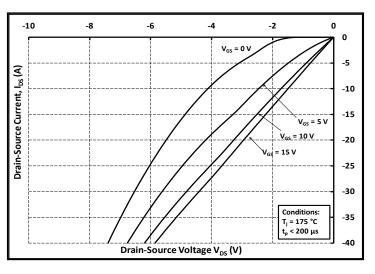


Figure 13. 3rd Quadrant Characteristic at -40 °C

Figure 14. 3rd Quadrant Characteristic at 25 °C



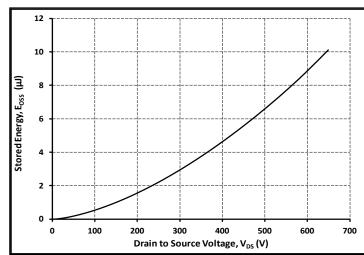
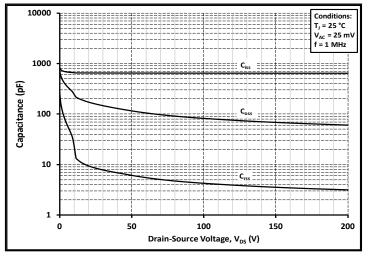


Figure 15. 3rd Quadrant Characteristic at 175 °C

Figure 16. Output Capacitor Stored Energy



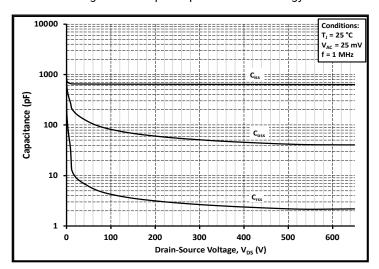
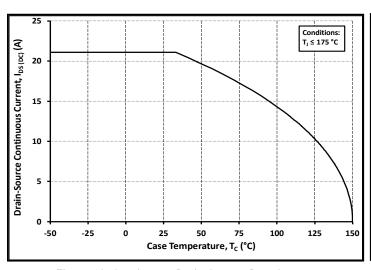


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

Figure 18. Capacitances vs. Drain-Source Voltage (0 - 650V)

Typical Performance

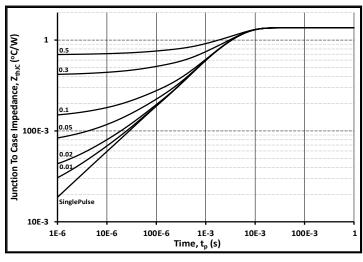


T_J ≤ 175 °C 80 Maximum Dissipated Power, P_{tot} (W) 70 50 40 30 20 10 -50 -25 75 100 125 150 25 50 Case Temperature, T_C (°C)

Conditions

Figure 19. Continuous Drain Current Derating vs. Case Temperature

Figure 20. Maximum Power Dissipation Derating vs. Case Temperature



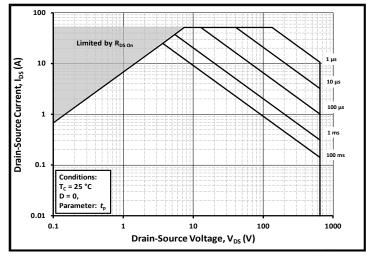
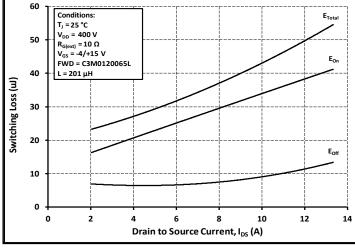


Figure 21. Transient Thermal Impedance (Junction - Case)

Figure 22. Safe Operating Area



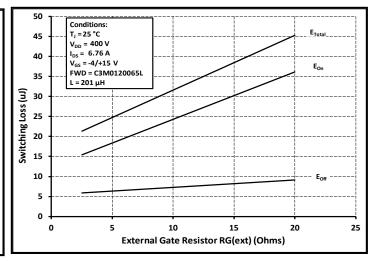


Figure 23. Clamped Inductive Switching Energy vs. Drain Current (V_{DD} = 400V)

Figure 24. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

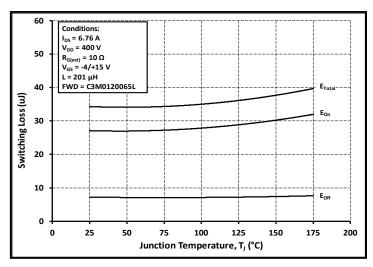


Figure 25. Clamped Inductive Switching Energy vs.
Temperature

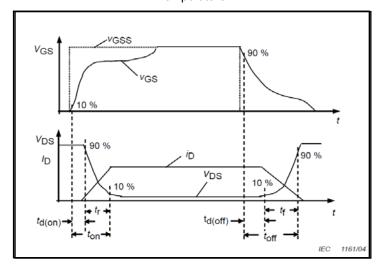


Figure 27. Switching Times Definition

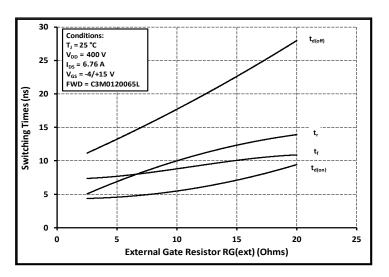


Figure 26. Switching Times vs. $R_{G(ext)}$

Test Circuit Schematic

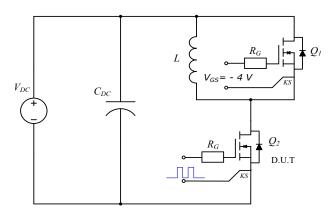
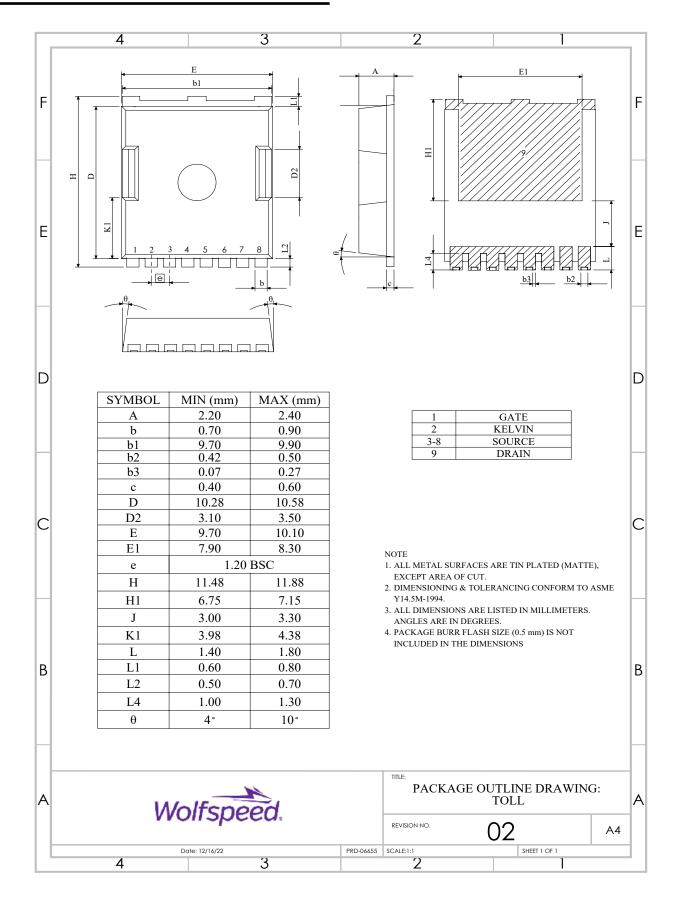


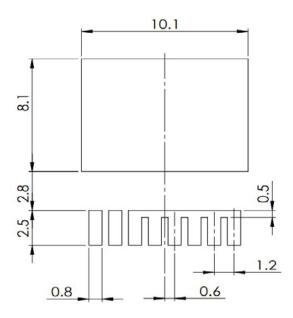
Figure 28. Clamped Inductive Switching Waveform Test Circuit

Package Dimensions



Recommended Solder Pad Layout

(Note: All Dimensions are listed in Millimeters)



Revision history

Document Version	Date of release	Description of changes
1.0	September-2022	Initial datasheet
2.0	November-2022	Correction in the placement of "E1" package dimension Orderable part number information added
3	December - 2024	Legal disclaimer, Table 1 layout revised

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